


**TSSOP-8**
**Pin Definition:**

1. Drain 1	8. Drain 2
2. Source 1	7. Source 2
3. Source 1	6. Source 2
4. Gate 1	5. Gate 2

**PRODUCT SUMMARY**

<b>V<sub>DS</sub> (V)</b>	<b>R<sub>DS(on)</sub>(mΩ)</b>	<b>I<sub>D</sub> (A)</b>
20	21 @ V <sub>GS</sub> = 4.5V	8
	25 @ V <sub>GS</sub> = 2.5V	7
	33 @ V <sub>GS</sub> = 1.8V	6

**Features**

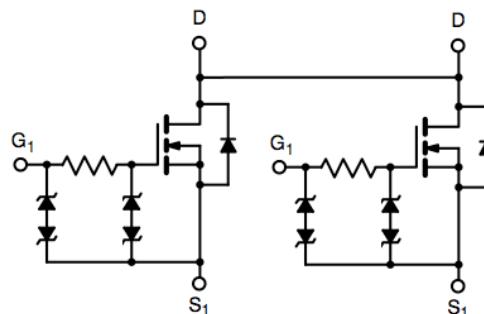
- Advance Trench Process Technology
- High Density Cell Design for Ultra Low On-resistance
- ESD Protect 2KV

**Application**

- Load Switch
- PA Switch

**Ordering Information**

<b>Part No.</b>	<b>Package</b>	<b>Packing</b>
TSM6970DCA RV	TSSOP-8	3Kpcs / 13" Reel

**Block Diagram**

**Dual N-Channel MOSFET**
**Absolute Maximum Rating (Ta = 25°C unless otherwise noted)**

<b>Parameter</b>	<b>Symbol</b>	<b>Limit</b>	<b>Unit</b>
Drain-Source Voltage	V <sub>DS</sub>	20	V
Gate-Source Voltage	V <sub>GS</sub>	±8	V
Continuous Drain Current, V <sub>GS</sub> @4.5V	I <sub>D</sub>	8	A
Pulsed Drain Current, V <sub>GS</sub> @4.5V	I <sub>DM</sub>	30	A
Continuous Source Current (Diode Conduction) <sup>a,b</sup>	I <sub>S</sub>	2.5	A
Maximum Power Dissipation	P <sub>D</sub>	2	W
		1.28	
Operating Junction Temperature	T <sub>J</sub>	+150	°C
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

**Thermal Performance**

<b>Parameter</b>	<b>Symbol</b>	<b>Limit</b>	<b>Unit</b>
Junction to Case Thermal Resistance	R <sub>θ<sub>JC</sub></sub>	30	°C/W
Junction to Ambient Thermal Resistance (PCB mounted)	R <sub>θ<sub>JA</sub></sub>	62.5	°C/W

**Notes:**

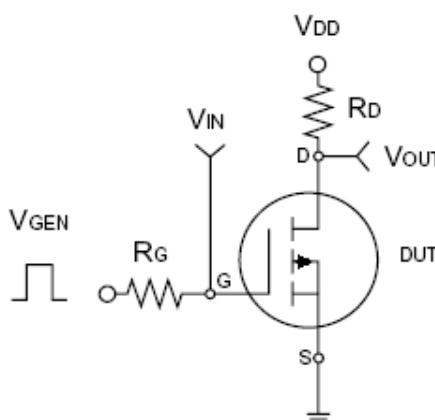
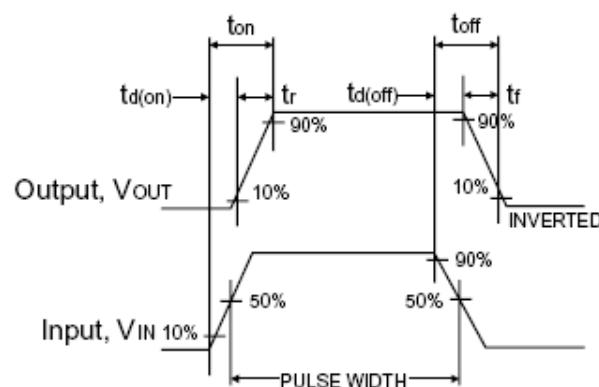
- Pulse width limited by the Maximum junction temperature
- Surface Mounted on FR4 Board, t ≤ 5 sec.

**Electrical Specifications**

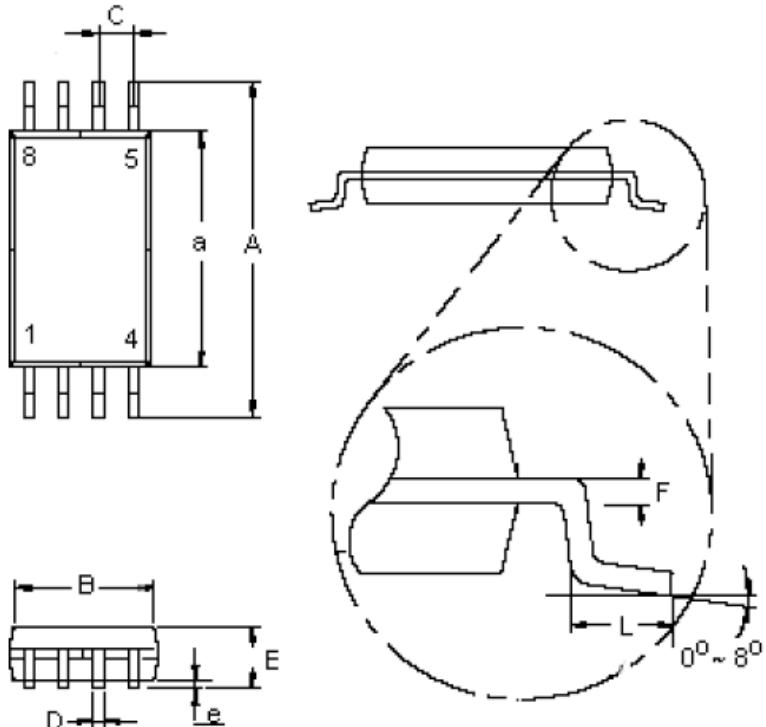
Parameter	Conditions	Symbol	Min	Typ	Max	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	$BV_{DSS}$	20	--	--	V
Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	$V_{GS(TH)}$	0.4	--	1	V
Gate Body Leakage	$V_{GS} = \pm 8V, V_{DS} = 0V$	$I_{GSS}$	--	--	$\pm 10$	$\mu A$
Zero Gate Voltage Drain Current	$V_{DS} = 16V, V_{GS} = 0V$	$I_{DSS}$	--	--	1	$\mu A$
On-State Drain Current	$V_{DS} = 5V, V_{GS} = 4.5V$	$I_{D(on)}$	10	--	--	A
Drain-Source On-State Resistance	$V_{GS} = 4.5V, I_D = 8A$	$R_{DS(on)}$	--	18	21	$m\Omega$
	$V_{GS} = 2.5V, I_D = 7A$		--	21	25	
	$V_{GS} = 1.8V, I_D = 6A$		--	26	33	
Forward Transconductance	$V_{DS} = 5V, I_D = 8A$	$g_{fs}$	--	13	--	S
Diode Forward Voltage	$I_S = 2.5A, V_{GS} = 0V$	$V_{SD}$	--	--	1.7	V
<b>Dynamic<sup>b</sup></b>						
Total Gate Charge	$V_{DS} = 10V, I_D = 8A, V_{GS} = 4.5V$	$Q_g$	--	13.8	--	$nC$
Gate-Source Charge		$Q_{gs}$	--	4.1	--	
Gate-Drain Charge		$Q_{gd}$	--	5.6	--	
Input Capacitance	$V_{DS} = 10V, V_{GS} = 0V, f = 1.0MHz$	$C_{iss}$	--	1160	--	$pF$
Output Capacitance		$C_{oss}$	--	104	--	
Reverse Transfer Capacitance		$C_{rss}$	--	29	--	
<b>Switching<sup>c</sup></b>						
Turn-On Delay Time	$V_{DD} = 10V, I_D = 1A, V_{GEN} = 4.5V, R_G = 3\Omega$	$t_{d(on)}$	--	140	200	$ns$
Turn-On Rise Time		$t_r$	--	210	250	
Turn-Off Delay Time		$t_{d(off)}$	--	3700	4800	
Turn-Off Fall Time		$t_f$	--	2000	2600	

**Notes:**

- pulse test: PW  $\leq 300\mu s$ , duty cycle  $\leq 2\%$
- For DESIGN AID ONLY, not subject to production testing.
- Switching time is essentially independent of operating temperature.


**Switching Test Circuit**

**Switching Waveforms**

**TSSOP-8 Mechanical Drawing**



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	6.20	6.60	0.244	0.260
a	4.30	4.50	0.170	0.177
B	2.90	3.10	0.114	0.122
C	0.65 (typ)		0.025 (typ)	
D	0.25	0.30	0.010	0.019
E	1.05	1.20	0.041	0.049
e	0.05	0.15	0.002	0.009
F	0.127		0.005	
L	0.50	0.70	0.020	0.028



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